

CUSTOMER: _____

DATE: _____

纳入仕様书 SPECIFICATION

产 品 名 称 PRODUCT NAME: 叠层片式天线

Multilayer Chip Antenna

贵 司 料 号 YOUR PART NO.: _____

敝 司 料 号 OUR PART NO.: MGMA3216H2450-A02

版 本 号 VERSION.: V2.0

接受 RECEPTION

THE SPECIFICATION HAS BEEN ACCEPTED.

该纳入仕様书已被我司接受

日期:
DATE:

公司:
COMPANY:

批准
CFMD

审核
CHKD

接收
RCVD

本纳入仕様书共 10 页

MANUFACTURING NAME

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目录 CATALOG

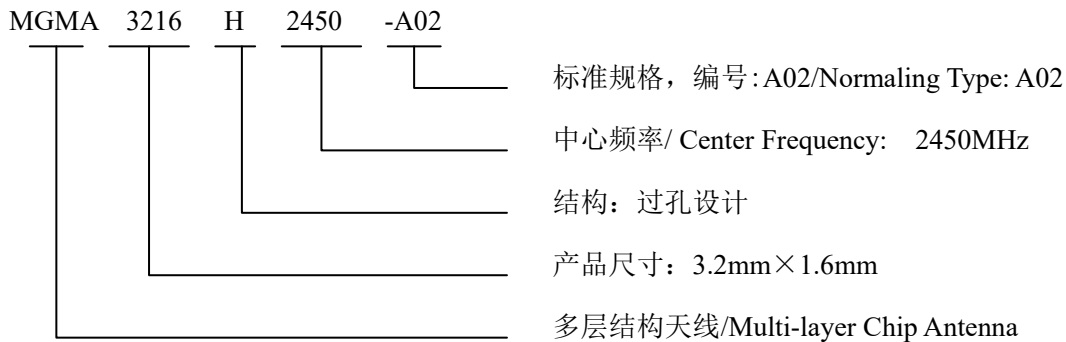
1 适用范围 Scope.....	3
2 品名构成 Product Identification.....	3
3 形状、尺寸 Appearance and Dimensions.....	3
4 测试电路及测试条件 Testing Conditions.....	3
5 电气性能 Electrical Characteristics.....	4
6 特性曲线 Characteristic curve.....	5
7 焊接条件 Recommended Soldering Conditions.....	6
8 包装 Packaging.....	7
9 保管 Storage.....	9
APPENDIX A	
纳入仕様书改定履历 Modify History of Specification	10

1 适用范围 Scope

"麦捷"微波叠层片式介质天线 MGMA 系列产品，设计用于 WLAN、HomeRF、Bluetooth、Module 等，小体积 SMD 片式设计。

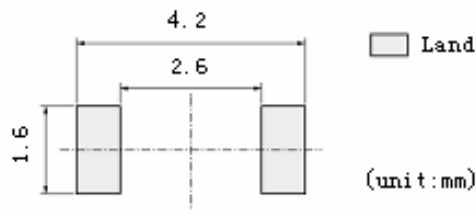
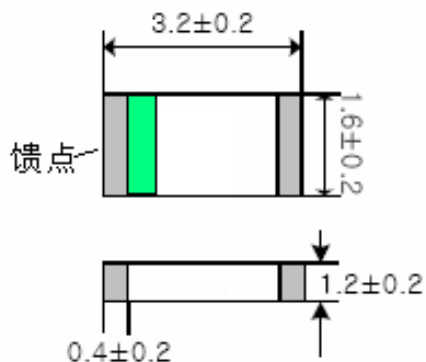
"Microgate" Microwave Multilayer Chip Antenna series are designed to be used in WLAN、HomeRF、Bluetooth、Module、etc, small size SMD chip design.

2 品名构成 Product Identification



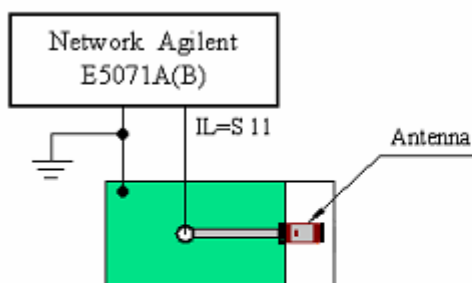
3 形状、尺寸 Appearance and Dimensions

Unit: mm

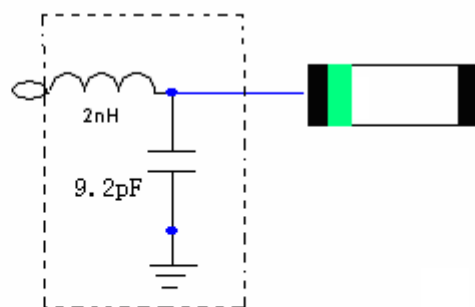


All the technical data and information specified herein are subject to variation without prior notice

4 测试电路及测试条件 Test Circuit and Testing Conditions



无匹配电路测试-3.5GHz中心频率
No Matching Circuit Testing



LC 匹配电路
LC Matching Circuit Testing

除非另有规定，否则在以下条件下测试 <Unless otherwise specified>

温度 Temperature : Ordinary Temperature (5 to 35℃)
 湿度 Humidity : Ordinary Humidity (25 to 85% RH)

大气压强 Atmospheric Pressure : 86 to 106 kPa

当对测量结果有疑问时<In case of doubt>

温度 Temperature : 20±2℃
 湿度 Humidity : 55 to 75% RH
 大气压强 Atmospheric Pressure : 86 to 106 kPa

5 电气性能 Electrical Characteristics

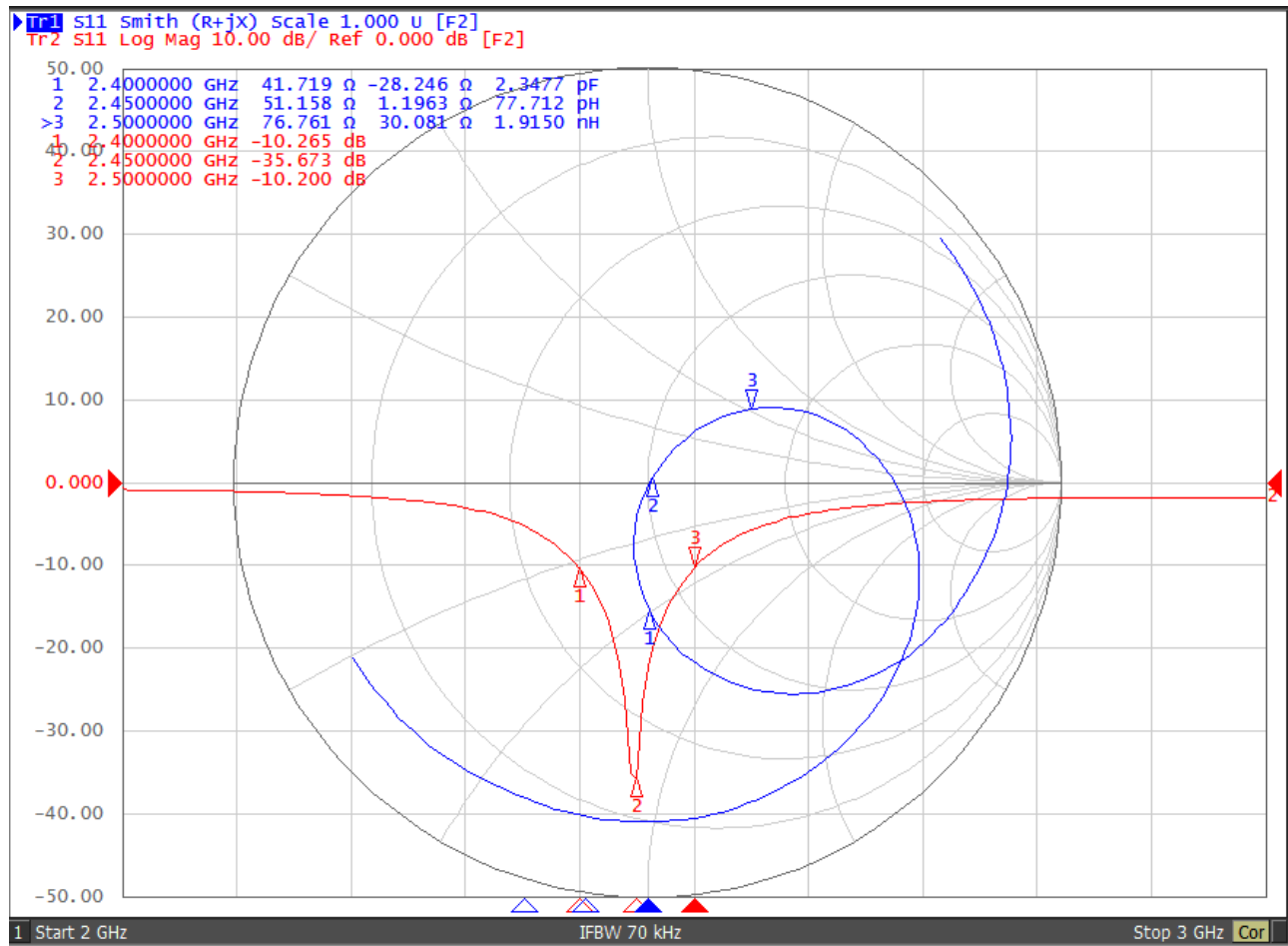
操作温度范围 Operating Temperature Range : -40 to +85℃

保存温度范围 Storage Temperature Range : -40 to +85℃

No.	Item (项目)	Specifications (特性)
1	Central Frequency 中心频率 (No matching)	3500MHz
	(带匹配电路测试)After Matching	2450 MHz
2	Band Width 通带宽度(No matching)	200 MHz (3400~3600MHz)
	(带匹配电路测试)After Matching	100 MHz (2400~2500MHz)
3	Gain 增益	0~2 dBi
4	V.S.W.R (in BW) 驻波比	≤2.0
5	Polarization 极化方式	Linear 线性
6	Azimuth Beam width 方位角	Omni-directional 全向
7	Impedance 阻抗	50 Ω

6 特性曲线 Characteristic curve

After Matching



7 焊接条件 Recommended Soldering Conditions

1、焊剂 Flux, Solder

① 使用松香助焊剂，禁止使用卤化物含量超过 0.2wt% 的强酸性助焊剂。

Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).

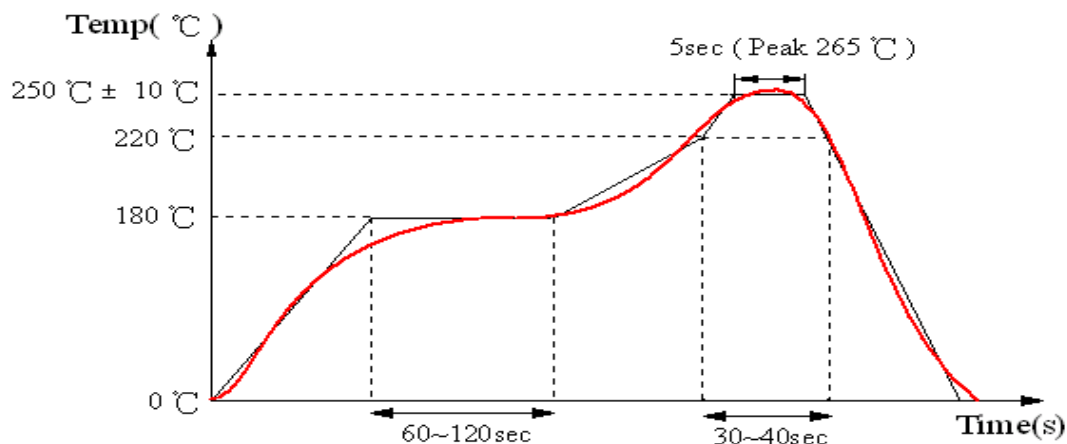
② 使用纯锡焊料 Use Sn solder.

2、回流焊条件 Reflow soldering conditions

● 预热时，产品表温与焊料温度的温差最大不允许超出 150℃，焊接完后冷却时，产品表温与溶剂温度之间的温差最大不允许超出 100℃。预热不足有可能引发产品表面裂纹，导致产品品质下降。

Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150℃ max. Cooling into solvent after soldering also should be in such a way that temperature difference is limited to 100℃ max. Unwrought pre-heating may cause cracks on the product, resulting in the deterioration of products quality.

● 标准回流焊曲线 Standard soldering profile.



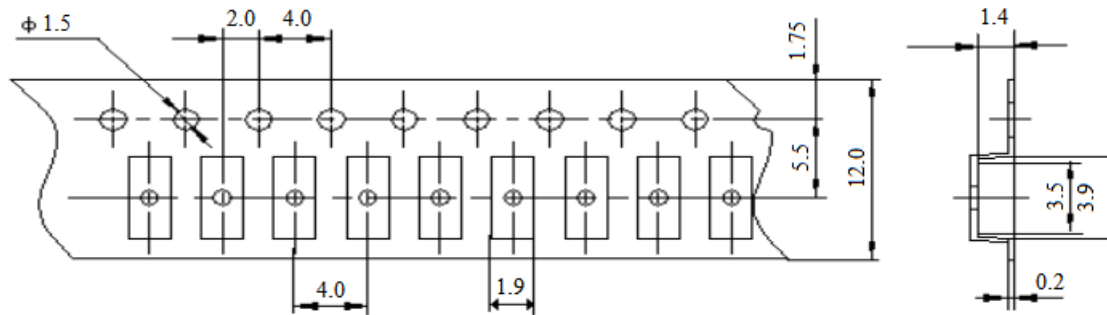
3、手工返工 Reworking with soldering iron

当使用电烙铁进行手工焊接时，以下条件必须严格遵守 The following conditions must be strictly followed when using a soldering iron.

预热 Pre-heating	150℃, 1 minute
尖端温度 Tip temperature	350℃ max
输出功率 Soldering iron output	80w max
电烙铁头尖端尺寸 End of soldering iron	φ3mm max
焊接时间 Soldering time	3 seconds max

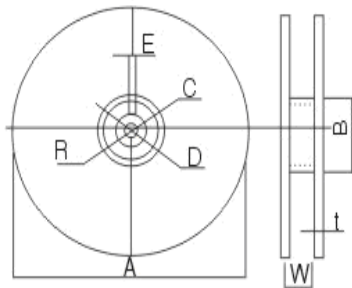
8 包装 Packaging

① 编带尺寸 Dimensions of Tape:



② 带轮尺寸 Dimensions of Reel

Unit: mm



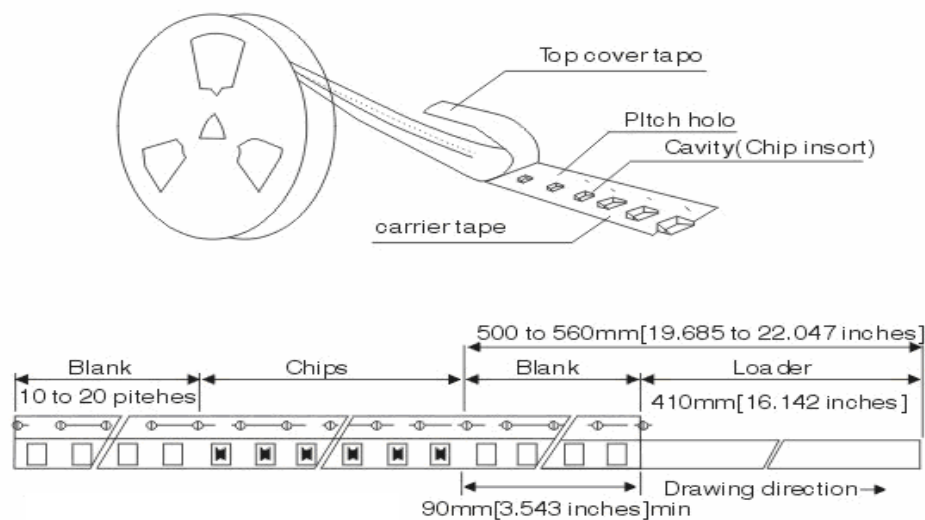
Reel material: PS (Polystyrene)

A	178 $\pm$ 2
B	60 $\pm$ 2
C	13.0 $\pm$ 0.5
D	21.0 $\pm$ 0.8
E	2.0 $\pm$ 0.5
W	12.5 $\pm$ 1.5
t	1.2 $\pm$ 0.2
R	1.0 $\pm$ 0.25

③ 编带抗拉强度 Pulling strength of tapes:

载带 Carrier tape	10N or more (1kgf or more)
上盖带 Cover tape	5N or more (1kgf or more)

④ 编带简图及拉伸方向 Taping figure and drawing direction:



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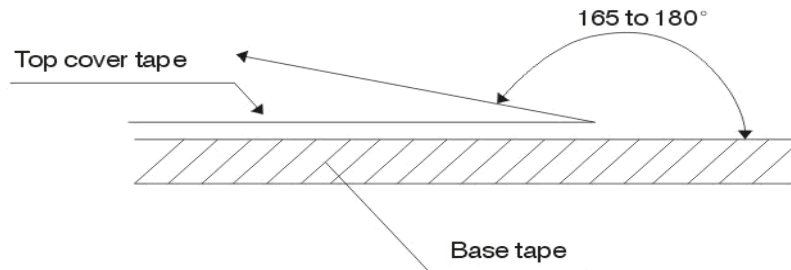
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⑤ 盖带的剥离强度 Peeling strength of cover tape:

盖带 Cover tape	0.3~0.7N (30gf~70gf)
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测试条件 Test condition:

- 1) 剥离角度 peel angle: 165°~180° vs. carrier tape.
- 2) 剥离速度 peel speed: 300mm/min±10%.

⑥ 包装数量 Packaging quantities: 3000 PCS / Reel

9 保管 Storage

①. 保管期限 Storage period

距麦捷出厂检验时间六个月内，产品可以使用；检验时间可以通过包装外侧标记的检验号确认；若时间超出六个月，应检查焊接性能后方可使用。Products which inspected in MICROGATE over 6 months ago should be examined and used, which can be confirmed with inspection No. marked on the container. Solder ability should be checked if this period is exceeded.

②. 保存条件 Storage conditions

●存放货物的库房应满足以下条件 Products should be storage in the warehouse on the following conditions

温度 Temperature: 10 ~40℃

湿度 Humidity : 30 to 70% relative humidity

不允许温、湿度有极剧变化。No rapid change on temperature and humidity

●禁止将产品保管在腐蚀性物质中，例如硫磺、氯气或者酸，否则将引起端头氧化，导致降低焊接性。Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solder ability.

●为了避免受潮气、灰尘等物质的影响，产品应保管于货架上。Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.

●产品保管在库房中时，应避免热冲击，振动以及直接光照等等。Products should be storage in the warehouse without heat shock, vibration, and direct sunlight and so on.

●产品应密封包装 Products should be storage under the airtight packaged condition.

